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*Text and photograph available at:* [*http://www.congatec.com/press*](http://www.congatec.com/press)

**Press release**

New congatec COM Express Computer-on-Module   
with 3 GHz Intel® Core™ i3 processor

**New cost efficient entry-level platform for   
high-end embedded computing**

**Deggendorf, Germany, 02 October 2018 \* \* \*** congatec – a leading vendor of standardized and customized embedded computer boards and modules – introduces a brand new price-breaking Computer-on-Module for the entry-level of high-end embedded computing based on Intel’s® latest Core™ i3-8100H processor platform. The new high-performance platform convinces with its optimized cost and performance-per-watt quad-core processor as well as support for low-power high-bandwidth DDR4 RAM. Its fast 16 PCIe Gen 3.0 lanes make it a perfect candidate for all the new artificial intelligence (AI) and machine learning applications requiring multiple GPUs for massive parallel processing. The integrated Intel® HD graphics UHD 630 is optimized in terms of clock rate and driver, which provides additional TDP headroom for even more GPGPU performance or 4k UHD graphics. All this makes the new COM Express Basic Computer-on-Module the performance-per-watt champion for price sensitive high-performance applications, that comes on demand with sophisticated passive or active cooling solutions from a single source.

Typical use cases range from all the manifold connected embedded, industrial, and IoT applications up to the brand new systems with embedded artificial intelligence that all require the latest high-end embedded performance with even greater energy and cost efficiency than the previously launched high-end Gen 8 Intel® Core™ i5 and Core™ i7 variants can provide.

"The 3 GHz quad-core Intel® Core™ i3 processor and the new HM370 Platform Controller Hub offer a particularly high performance per watt ratio as well as an unbeaten performance per dollar ratio," explains Martin Danzer, Director of Product Management at congatec. “The price has fallen significantly – so customers can now serve even the most computational intensive AI applications at an affordable price level.”

**The feature set in detail**

The new conga-TS370 COM Express Basic Type 6 Computer-on-Module with quad-core Intel® Core™ i3 8100H processor offers a 45 watt TDP configurable to 35 W, supports 6 MB cache and provides up to 32 GB dual-channel DDR4 2400 memory. Compared to the preceding 7th generation of Intel® Core™ processors, the improved memory bandwidth also helps to increase the graphics and GPGPU performance of the integrated new Intel® UHD630 graphics, which additionally features an increased maximum dynamic frequency of up to 1.0 GHz for its 24 execution units. It supports up to three independent 4K displays with up to 60 Hz via DP 1.4, HDMI, eDP and LVDS. For the first time, designers can now switch from eDP to LVDS purely by modifying the software without any hardware changes. The module further provides exceptionally high bandwidth I/Os including 4x USB 3.1 Gen 2 (10 Gbit/s), 8x USB 2.0 and 1x PEG and 8 PCIe Gen 3.0 lanes for powerful system extensions including Intel® Optane™ memory. All common Linux operating systems as well as the 64-bit versions of Microsoft Windows 10 and Windows 10 IoT are supported. congatec’s unique personal integration support rounds off the feature set. Additionally, congatec also offers an extensive range of accessories and comprehensive technical services, which simplify the integration of new modules into customer-specific solutions.

The new module is now available worldwide in the following standard configuration:

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| **Processor** |  | **Cores/ Threads** |  | **Clock [GHz] (Base/cTDP down)** |  | **Cache (MB)** |  | **GPU Compute Units** |  | **TDP/ cTDP [W]** |
| Intel® Core™ i3-8100H |  | 4 / 4 |  | 3.0 / 2.6 |  | 6 |  | 24 |  | 45 / 35 |

More information about the new conga-TS370 high-performance COM Express Type 6 Computer-on-Modules is available at: <https://www.congatec.com/products/com-express-type6/conga-ts370.html>

**About congatec**congatec is a leading supplier of industrial computer modules using the standard form factors COM Express, Qseven and SMARC as well as single board computers and customizing services. congatec’s products can be used in a variety of industries and applications, such as industrial automation, medical, entertainment, transportation, telecommunication, test & measurement and point-of-sale. Core knowledge and technical know-how includes unique extended BIOS features as well as comprehensive driver and board support packages. Following the design-in phase, customers are given support via extensive product lifecycle management. The company’s products are manufactured by specialist service providers in accordance with modern quality standards. Headquartered in Deggendorf, Germany, congatec currently has entities in USA, Taiwan, China, Japan and Australia as well as United Kingdom, France, and the Czech Republic. More information is available on our website at [www.congatec.com](http://www.congatec.com/) or via [Facebook](http://www.facebook.com/Congatec), [Twitter](https://mobile.twitter.com/congatecAG) and [YouTube](http://www.youtube.com/congatecAE).

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